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**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Application No. : 10/667,825 Confirmation No.: 1009**  
**Applicant(s) : Giuseppe Pedretti, et al.**  
**Filed : September 22, 2003**  
**TC/A.U. : 3729**  
**Examiner : Thiem D. Phan**  
**Title : Process for Manufacture of Printed Circuit Boards with Thick Copper Power Circuitry**  
**Docket No. : 8245.060**  
**Customer No. : 30589**

**Mail Box Fee Amendment**  
**Commissioner for Patents**  
**P.O. Box 1450**  
**Alexandria, VA 22313-1450**

**RESPONSE**

In response to the Office Action dated March 30, 2006, Applicants submit the following:

**Listing of Claims** begins on page **2** of this paper.

**Remarks/Arguments** begin on page **8** of this paper.